

# COMPANY PRESENTATION

H1 2024

PVA TePla





# HIGHLIGHTS H1 2024

## PROGRESS ON THE DEVELOPMENT OF OUR ORGANIZATION

- ❖ We continued to win **new long-term metrology-customers** in the semiconductor and automotive industry
- ❖ Technology hub successfully launched **with initial focus on SiC**
- ❖ Establishment of a strong **technology driven second level management**
- ❖ **Carl Markus Groß** appointed as CFO as of 1 January 2025
- ❖ **Capacity Expansion:** Construction of the new plants in Wettenberg (Germany) and Schio (Italy) almost completed

# KEY FIGURES FOR H1 2024

## STRONG H1 2024 WITH SIGNIFICANTLY IMPROVED PROFITABILITY



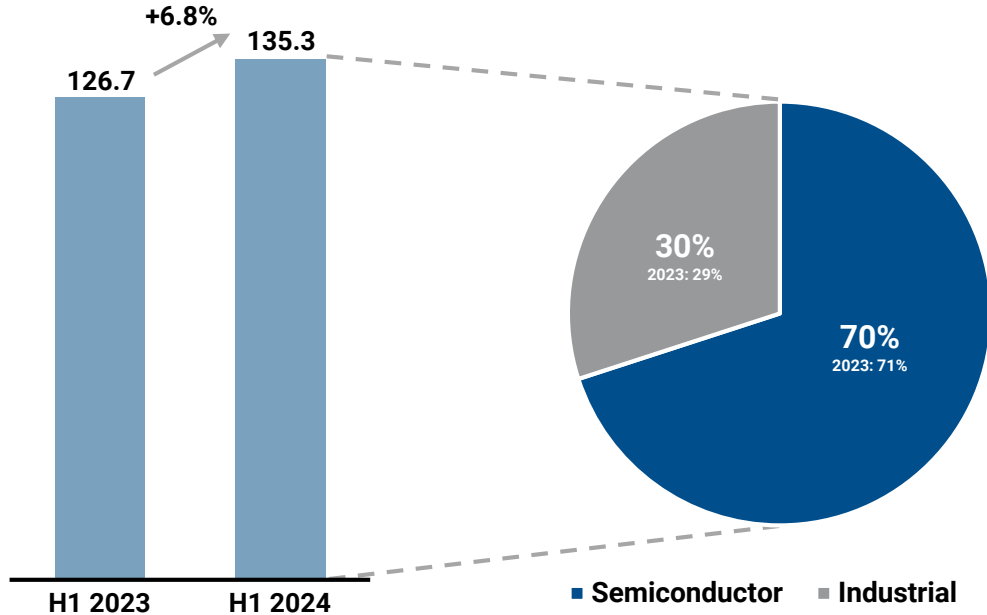
- ▶ **Sales in line with expectations** at 6.8% growth
- ▶ Profitability improved: **H1 EBITDA margin at 16.2%**, up from 13.8% last year
- ▶ Order intake down 30.9%, mainly due to wafer weakness, while **metrology business is continuously growing**
- ▶ **On track with investments** in infrastructure, workforce, capacity and innovation to support sustainable future growth

# GROUP SALES

## IN LINE WITH EXPECTATIONS

Year to Year  
[EURm]

Segment Split  
[EURm]



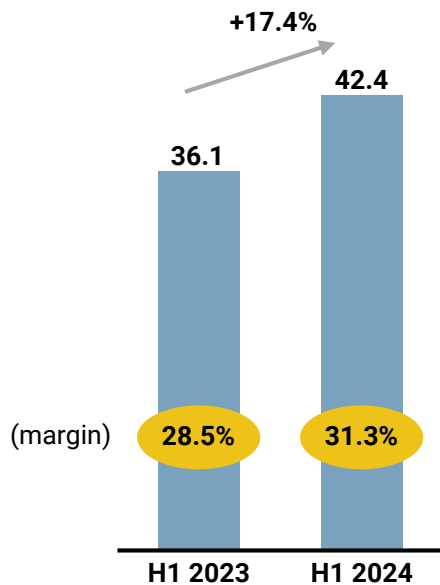
- ▶ Semiconductor grew by **5.6%**, Industrial segment by **9.7% y/y**
- ▶ Both segments **benefit from megatrends**, e.g. digitization, e-mobility, renewable energies
- ▶ Becoming **less dependent** on specific sector cycles by generating **revenue from a variety of sectors**
- ▶ Regional sales split: **Asia 55%**, **Germany 6%**, **Europe (ex-Germany) 25%**, **America 13%**

# GROUP PROFIT

## PROFITABILITY CLEARLY OUTPACES SALES GROWTH

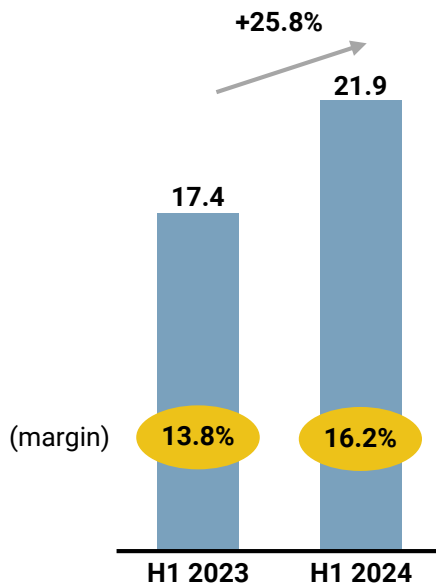
### Gross Profit

[EURm]



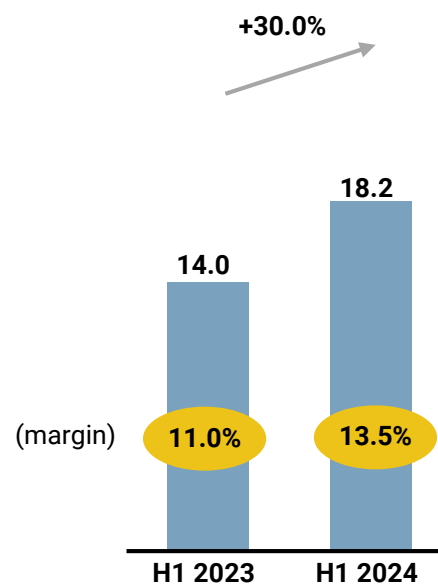
### EBITDA

[EURm]



### EBIT

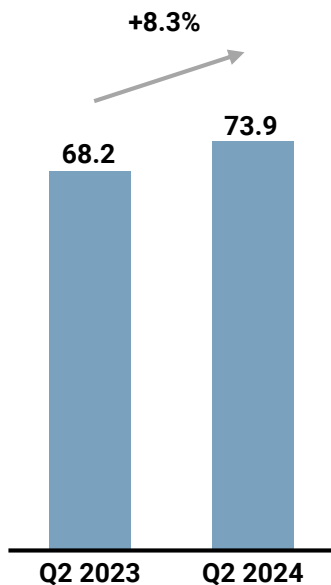
[EURm]



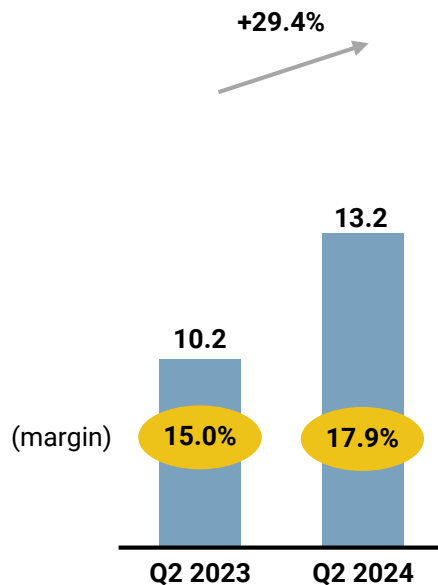
# QUARTERLY DEVELOPMENT

MARGIN IMPROVEMENT VS. PREVIOUS YEAR AS WELL AS PREVIOUS QUARTER

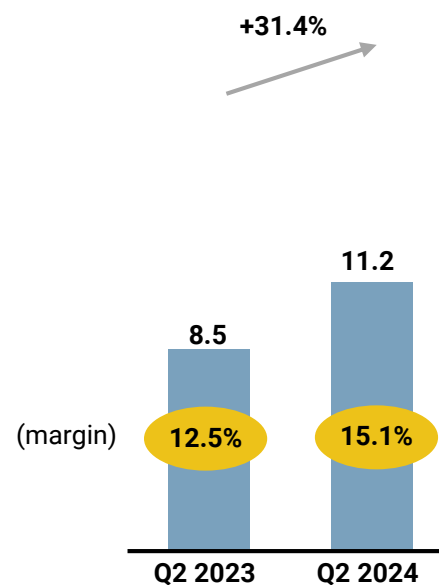
Sales  
[EURm]



EBITDA  
[EURm]



EBIT  
[EURm]

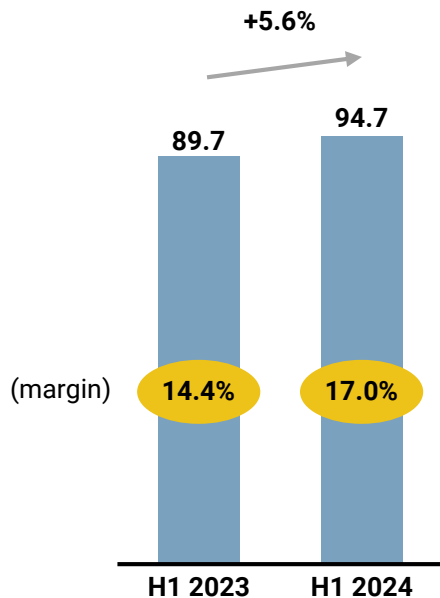


# SEMICONDUCTOR

## SUBSTANTIAL EBIT-MARGIN IMPROVEMENT

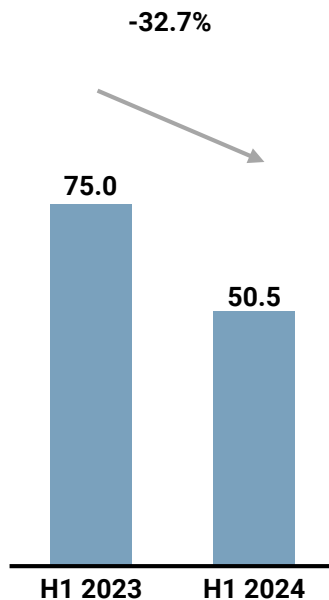
### Sales and EBIT margin

[EURm]



### Order intake

[EURm]



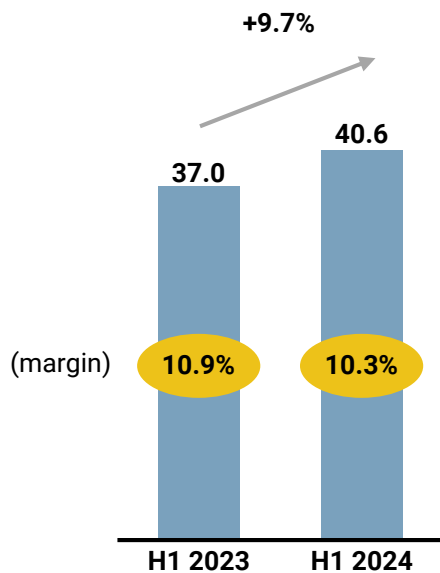
- ▶ Solid sales growth
- ▶ Very good **profitability improvement** in excess of group average
- ▶ Order intake affected by weakness in the semiconductor industry
- ▶ **Order Backlog at 129.2 m, -36.7% YoY**

# INDUSTRIAL

## LOWER ORDER INTAKE AT CLOSING DATE, BUT ORDER BACKLOG AT A SOLID LEVEL

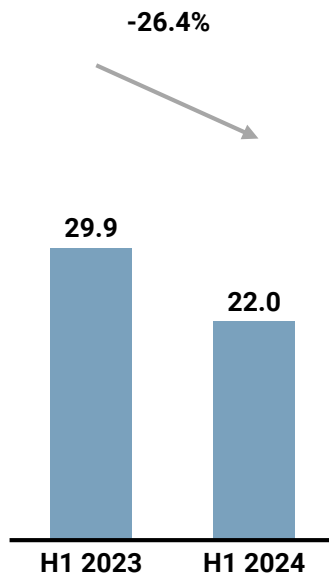
### Sales and EBIT margin

[EURm]



### Order intake

[EURm]



- ▶ **Sound and over-proportional sales growth** compared to group level
- ▶ **EBIT up to 4.2 m** with EBIT margin above 10%
- ▶ Order intake at 22 m due to **longer customer award processes**
- ▶ Order backlog at 85.2 m, -9.1% YoY

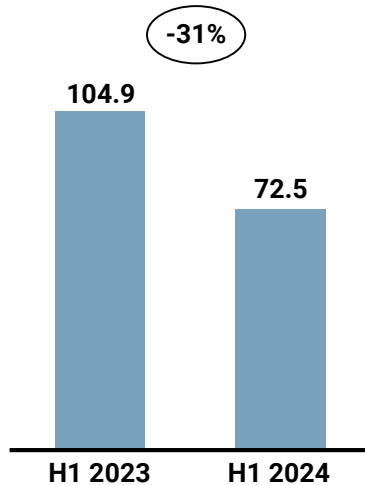


# ORDER INTAKE

## STRONG DEMAND IN METROLOGY, MATERIAL SOLUTIONS TO PICK UP IN H2

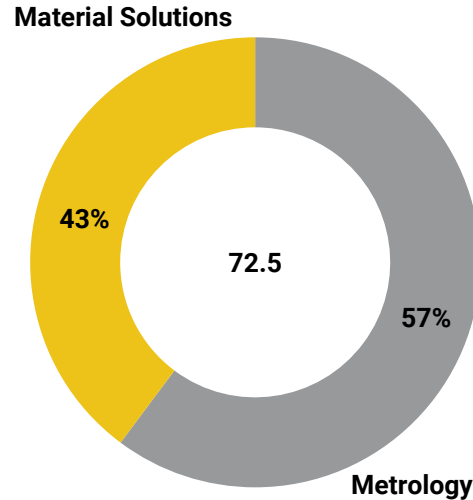
### Year to Year

[EURm]



### Product Line

[EURm / %]



- ▶ Semiconductor industry is still in recovery mode, **acceleration now expected in H2**
- ▶ **Semiconductor** contributes **70%** of new orders, **Industrial 30%**
- ▶ Well diversified order book: **Asia 38%**, **Germany 19%**, **Europe (ex-Germany) 19%**, **America 25%**

**MAJOR GROWTH DRIVER**

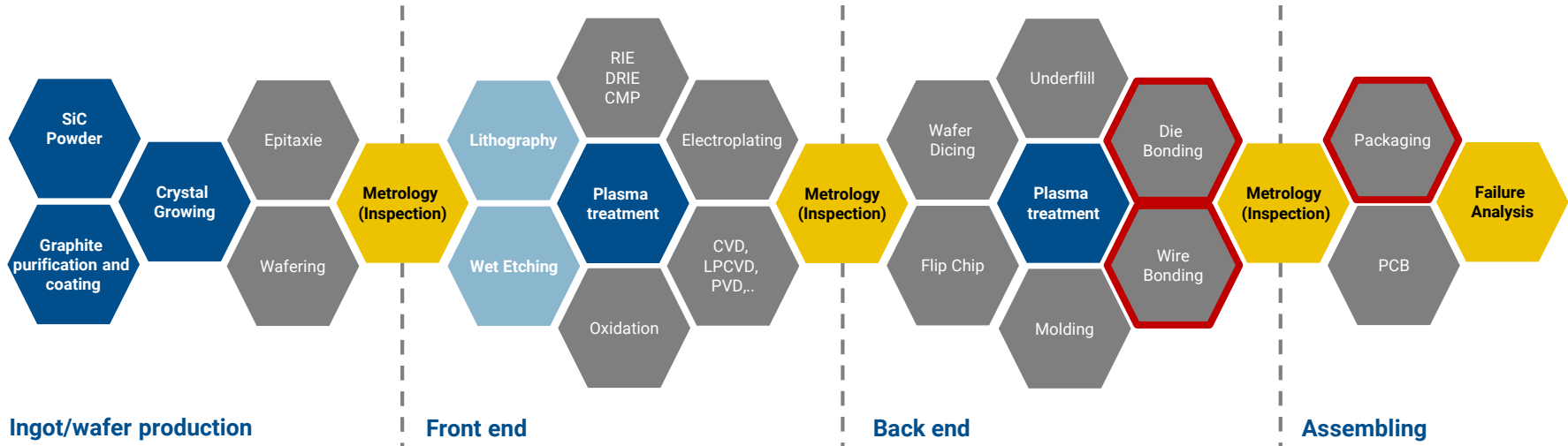
**ACOUSTIC METROLOGY**

**PVA**  **TePla**



# DEEPLY EMBEDDED AT KEY STAGES OF THE SEMICONDUCTOR VALUE CHAIN

PROVIDING LEADING SYSTEMS AND SOLUTIONS IN SYNTHESIS, JOINING, REFINING, SURFACE TREATMENT AND METROLOGY



■ Material Solutions: Synthesis, Surface Treatment, Refining

■ Metrology: Ultrasound, VPD, Laser, and Optical

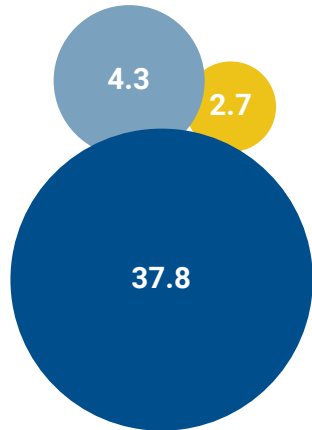
■ Material Solutions: indirect involvement through Joining and Synthesis technologies

# EXCURSUS: SCANNING ACOUSTIC MICROSCOPY (SAM)

## OUTLOOK FOR SELECTED TARGET MARKETS

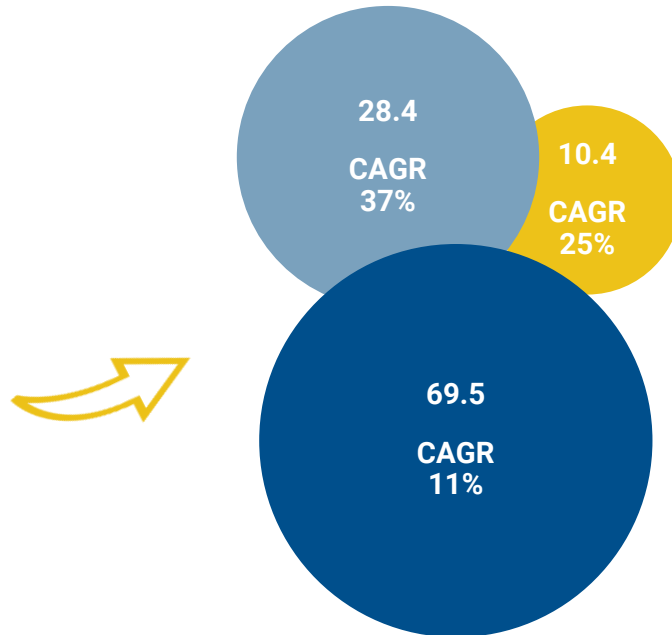
### Market volume 2023

[EUR bn]



### Market volume 2029e

[EUR bn]



■ Advanced Packaging   ■ High-End Packaging   ■ SiC Mosfet

- ▶ Scanning acoustic microscopy uses **high-frequency ultrasound** for non destructive microscopic analysis of materials and components
- ▶ Our metrology systems **address multi-billion dollar growth markets** such as advanced packaging, high-end packaging and power electronics
- ▶ In addition, we are **already present** in a number of other attractive markets such as **memory, sensors, LEDs, IGBTs** etc., growing at an CAGR of around 10%



Leading the way in ultrasound  
microscopy technology

## OUR SUPERIOR TECHNOLOGY

### PRECISION, FLEXIBILITY AND INNOVATION

- ▶ **High-Resolution Imaging:** Detects smallest defects in semiconductor components
- ▶ **Versatile Applications:** Suitable for semiconductors, composites, and components
- ▶ **Advanced NDT:** Leaders in non-destructive testing without material damage
- ▶ **Customized Solutions:** Tailored systems for specific customer needs
- ▶ **High level of automization:** Using artificial intelligence
- ▶ **Higher throughput:** due to multi-channel solution & dual gantry

# FULL-YEAR GUIDANCE

## CONFIRMED

- **Recovery of Semiconductor Industry** expected in late 2024
- FY2024 **sales target** between **EUR 270m and EUR 290m** with earnings before interest, tax, depreciation and amortization (**EBITDA**) ranging from **EUR 47m to EUR 51m**



# TIME FOR YOUR QUESTIONS







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